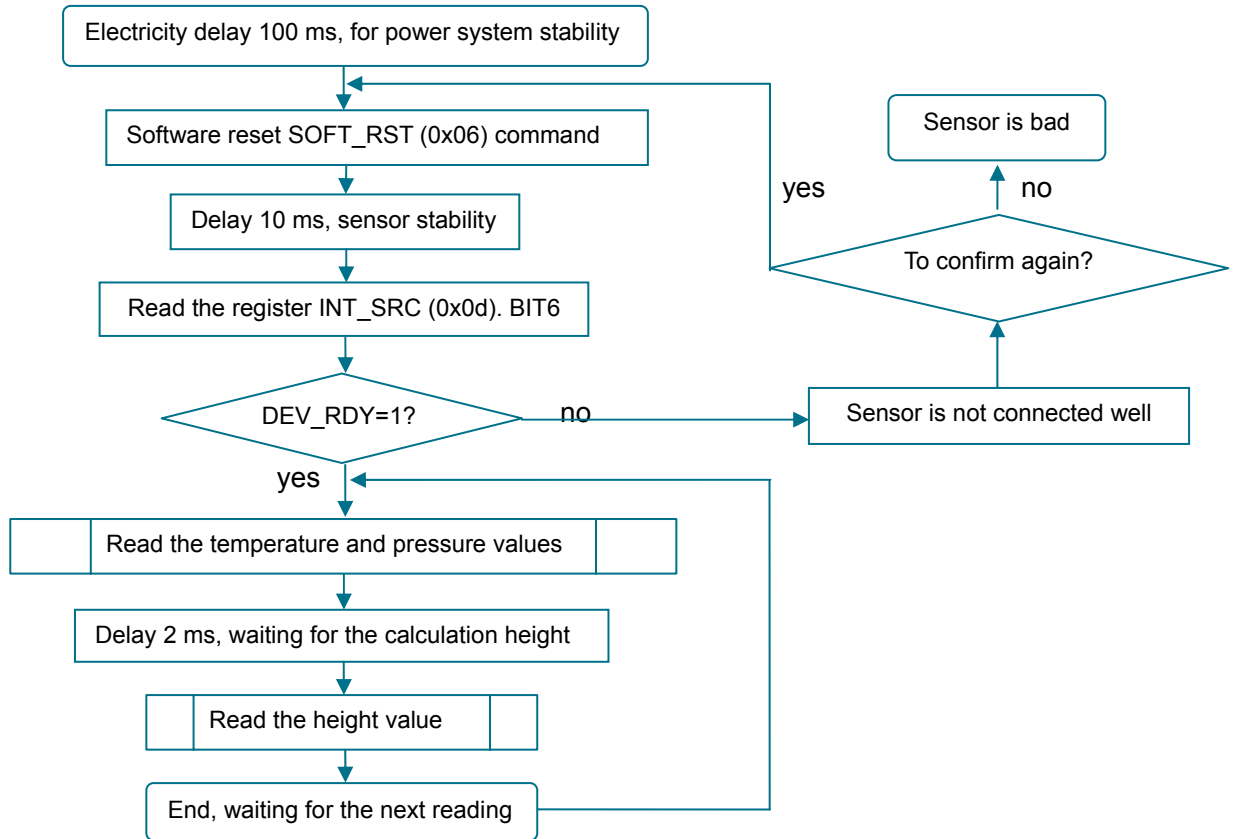
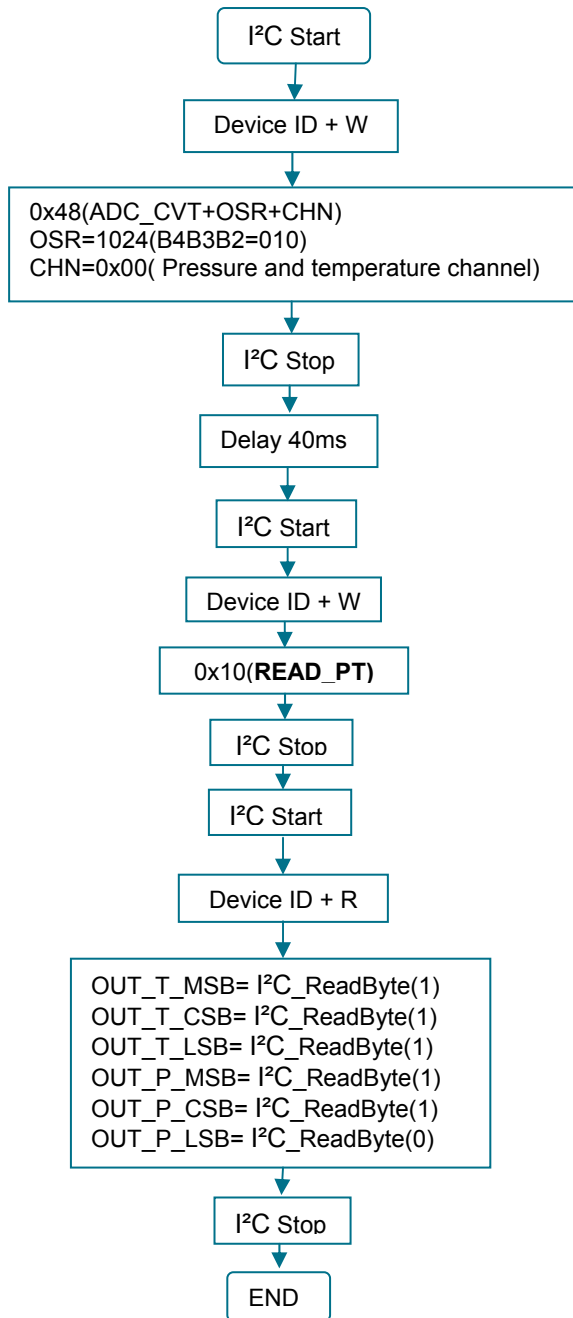


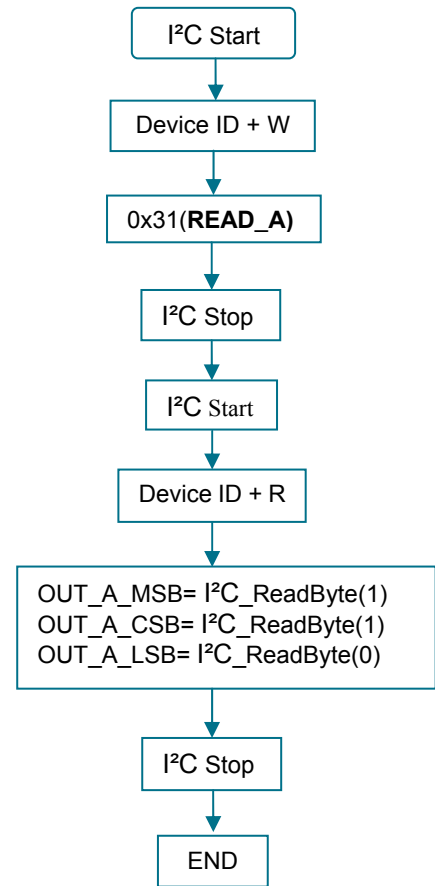
Flow Chart



Read the temperature and pressure values



Read the height value



Notes: **HP203B**

Device ID: **CSB PIN=0:** 0xEE(write) and 0xEF(read).
CSB PIN=1: 0xEC(write) and 0xED(read).

Soldering note of HP203B sensor:

1. The products can be soldered in 40 seconds under 250°C. In order to avoid damage to the sensor, soldering temperature is as low as possible and heating time is as short as possible; Recommend use the low temperature solders.
2. The HP203B require stabilization for 5 to 7 days to recover after SMT soldering due to the sensor pressure stabilization will be effected by the heat, assembly stress.
3. The manual solder cannot ensure uniformity for the time, temperature, heating. These factors will degrade or damage the sensor.
4. The electrical contact pads are protected against ESD up to 2 kV HBM (human body model). It is therefore essential to ground machines and personnel properly during assembly and handling of the device.

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Rev: HP203B_Product Development Guide_V2.0